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STMicroelectronics STTH12S06FP

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STTH12S06

Turbo 2 ultrafast high voltage rectifier

Table 1. Main product characteristics

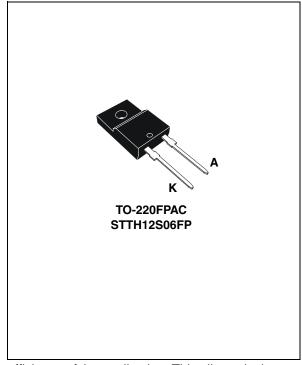
| I _{F(AV)} | 12 A |
|------------------------|--------|
| V _{RRM} | 600 V |
| I _{RM (typ.)} | 6 A |
| T _{j (max)} | 175 °C |
| V _{F (typ)} | 1.5 V |
| t _{rr (typ)} | 14 ns |

Features and benefits

- Ultrafast recovery
- Low reverse recovery current
- Reduces losses in diode and switching transistor
- Low thermal resistance
- Higher frequency operation
- Insulated voltage: 1500 V_{RMS}

Description

ST's STTH12S06 is a state of the art Ultrafast recovery diode. By the use of 600 V Pt doping Planar technology, this diode will outperform the power factor correction circuits operating in hardswitching conditions. The extremely low reverse recovery current of the STTH12S06, reduces significantly the switching power losses of the MOSFET, and thus increases the



efficiency of the application. This allows designers to reduce the size of their heatsinks.

This device is also intended for applications in power supplies and power conversions systems, and other power switching applications.

Table 2. Absolute ratings (limiting values at 125 °C, unless otherwise stated)

| Symbol | Parameter | Value | Unit |
|---------------------|--|------------|------|
| V _{RRM} | Repetitive peak reverse voltage | 600 | V |
| I _{F(AV}) | Average forward current | 12 | Α |
| I _{FSM} | Surge non repetitive forward current | 100 | Α |
| T _{stg} | Storage temperature range | - 65 + 175 | °C |
| T _j | Maximum operating junction temperature | 175 | °C |

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Characteristics STTH12S06

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Table 3. Thermal resistances

| Symbol | Parameter | Value | Unit |
|-----------|------------------|-------|------|
| Rth (j-c) | Junction to case | 4.6 | °C/W |

Table 4. Static electrical characteristics

| Symbol | Parameter | Tests conditions | | Min. | Тур. | Max. | Unit |
|--|-------------------------------------|-------------------------|-------------------------|------|------|------|------|
| I_ | Reverse leakage current | V _R = 600 V | T _j = 25 °C | | | 30 | μA |
| I _R Reverse leakage current | V _R = 000 V | T _j = 125 °C | | 35 | 400 | μΛ | |
| V _F | V _F Forward voltage drop | I _E = 12 A | T _j = 25 °C | | | 3.4 | V |
| V _F Forward vo | Forward vollage drop | IF = 12 A | T _j = 150 °C | | 1.5 | 1.9 | V |

 Table 5.
 Dynamic electrical characteristics

| Symbol | Tests conditions | | Min. | Тур. | Max. | Unit |
|-----------------|--|-------------------------|------|------|------|------|
| t _{rr} | $I_F = 1 \text{ A} \text{ d}I_F/\text{d}t = -200 \text{ A/}\mu\text{s} \text{ V}_R = 30 \text{ V}$ | | | 14 | 21 | ns |
| I _{RM} | $V_R = 400 \text{ V}$ $I_F = 12\text{A}$ $dI_F/dt = -200 \text{ A/}\mu\text{s}$ | _ | | 6.0 | 8.0 | Α |
| S factor | V _R = 200 V I _F = 12A | T _j = 125 °C | | 0.3 | | |
| Q _{rr} | $dI_F/dt = -200 A/\mu s$ | | | 160 | | nC |

Figure 1. Conduction losses versus average current

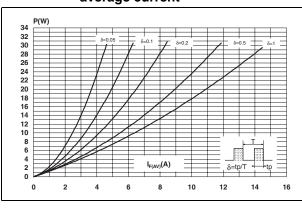
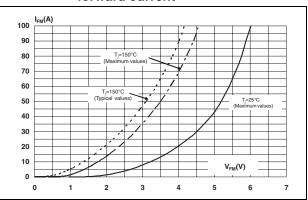


Figure 2. Forward voltage drop versus forward current

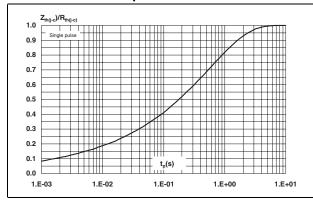




STTH12S06 Characteristics

Figure 3. Relative variation of thermal impedance, junction to case, versus pulse duration

Figure 4. Peak reverse recovery current versus dl_F/dt (typical values)



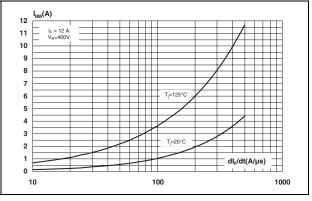
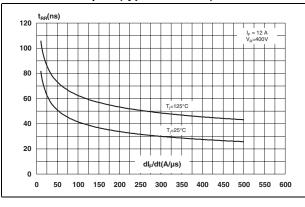


Figure 5. Reverse recovery time versus dl_F/dt (typical values)

Figure 6. Reverse recovery charges versus dI_F/dt (typical values)



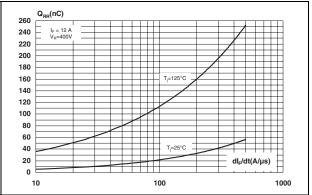
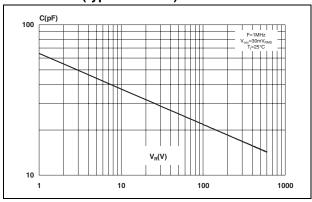


Figure 7. Junction capacitance versus reverse voltage applied (typical values)





Package information STTH12S06

2 Package information

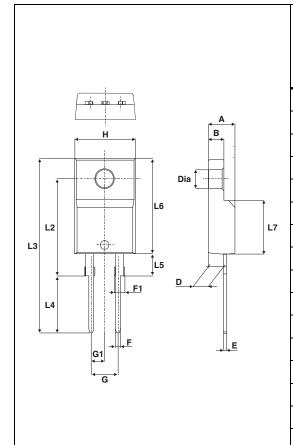
Epoxy meets UL94, V0

Cooling method: by conduction (C)Recommended torque value: 0.55 Nm

Maximum torque value: 0.7 Nm

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Table 6. TO-220FPAC dimensions



| | Dimensions | | | | |
|------|-------------|------|-------|-------|--|
| Ref. | Millimeters | | Inc | hes | |
| | Min. | Max. | Min. | Max. | |
| Α | 4.4 | 4.6 | 0.173 | 0.181 | |
| В | 2.5 | 2.7 | 0.098 | 0.106 | |
| D | 2.5 | 2.75 | 0.098 | 0.108 | |
| Е | 0.45 | 0.70 | 0.018 | 0.027 | |
| F | 0.75 | 1 | 0.030 | 0.039 | |
| F1 | 1.15 | 1.70 | 0.045 | 0.067 | |
| G | 4.95 | 5.20 | 0.195 | 0.205 | |
| G1 | 2.4 | 2.7 | 0.094 | 0.106 | |
| Η | 10 | 10.4 | 0.393 | 0.409 | |
| L2 | 16 | Гур. | 0.63 | Тур. | |
| L3 | 28.6 | 30.6 | 1.126 | 1.205 | |
| L4 | 9.8 | 10.6 | 0.386 | 0.417 | |
| L5 | 2.9 | 3.6 | 0.114 | 0.142 | |
| L6 | 15.9 | 16.4 | 0.626 | 0.646 | |
| L7 | 9.00 | 9.30 | 0.354 | 0.366 | |
| Dia. | 3.00 | 3.20 | 0.118 | 0.126 | |



STTH12S06 Ordering information

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 Table 7.
 Ordering information

| Part number | Marking | Package | Weight | Base qty | Delivery mode |
|-------------|-------------|------------|--------|----------|---------------|
| STTH12S06FP | STTH12S06FP | TO-220FPAC | 1.64 | 50 | Tube |

4 Revision history

Table 8. Revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 02-Oct-2007 | 1 | Initial release. |



Distributor of STMicroelectronics: Excellent Integrated System Limited Datasheet of STTH12S06FP - DIODE GEN PURP 600V 12A TO220FP

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STTH12S06

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